

(0.80 mm) .0315"

QTE SERIES

HIGH-SPEED GROUND PLANE HEADER

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?QTE

Insulator Material: Liquid Crystal Polymer
Terminal Material: Phosphor Bronze

Plating: Au or Sn over 50 μ" (1.27 μm) Ni
Current Rating: Contact: 2 A per pin (2 pins powered) Ground Plane: 23 A per ground plane (1 ground plane powered)

Operating Temp Range: -55 °C to +125 °C
Voltage Rating: 225 VAC mated with QSE & 5 mm Stack Height
Max Cycles: 100

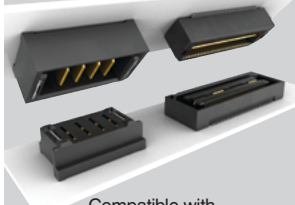
RoHS Compliant: Yes

Board Mates: QSE

Cable Mates: EQCD, EQDP (See Also Available Note)

Standoffs: SO

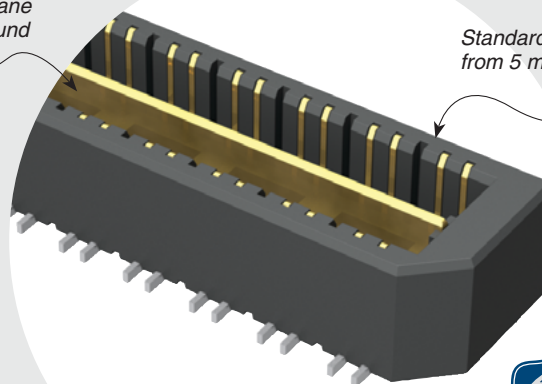
POWER/SIGNAL APPLICATION



Compatible with UMP/T/UMPS for flexible two-piece power/signal solutions

Integral metal plane for power or ground

Standard stack heights from 5 mm to 25 mm



HIGH-SPEED CHANNEL PERFORMANCE

QTE-D/QSE-D or QTE-DP/QSE-DP @ 5 mm Mated Stack Height

Rating based on Samtec reference channel. For full SI performance data visit Samtec.com/contact SIG@samtec.com

14 Gbps

28 Gbps

PROCESSING

Lead-Free Solderable: Yes
SMT Lead Coplanarity: (0.10 mm) .004" max (020-060)
Board Stacking: For applications requiring more than two connectors per board contact ipg@samtec.com

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



ALSO AVAILABLE (MOQ Required)

- 15 mm, 22 mm and 30 mm stack height
- 30 μ" (0.76 μm) Gold (Specify -H plating for Data Rate cable mating applications.)
- Edge Mount, Guide Posts, Screw Down & Friction Lock
- 56 (-DP), 80, 100 positions per row
- Retention Option

Note: Some lengths, styles and options are non-standard, non-returnable.

QTE - PINS PER ROW NO. OF PAIRS - LEAD STYLE - PLATING OPTION - TYPE - A - OTHER OPTION

-020, -040, -060 (40 total pins per bank = -D)

-014, -028, -042 (14 pairs per bank = -D-DP)

Specify LEAD STYLE from chart

-F = Gold Flash on Signal Pins and Ground Plane, Matte Tin on tails

-L = 10 μ" (0.25 μm) Gold on Signal Pins and Ground Plane, Matte Tin on tails

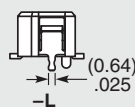
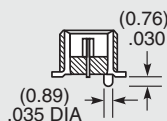
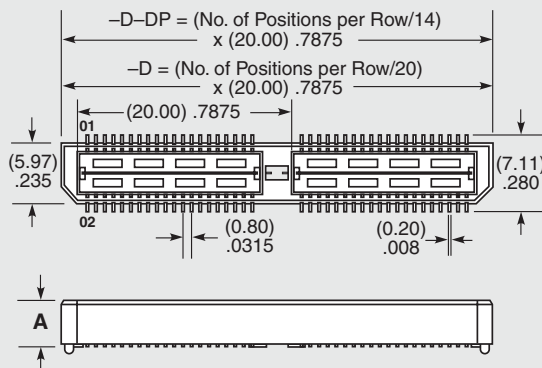
-C* = Electro-Polished Selective 50 μ" (1.27 μm) min Au over 150 μ" (3.81 μm) Ni on Signal Pins in contact area, 10 μ" (0.25 μm) min Au over 50 μ" (1.27 μm) Ni on Ground Plane in contact area, Matte Tin over 50 μ" (1.27 μm) min Ni on all solder tails

-D = Single-Ended
 -D-DP = Differential Pair (-01 only)

-K = (7.00 mm) .275" DIA Polyimide Film Pick & Place Pad

-TR = Tape & Reel Packaging (N/A -05 & -07 lead style)

-L = Latching Option (N/A on -042 & -060 positions)



***Note:** -C Plating passes 10 year MFG testing

QTE LEAD STYLE	A	HEIGHT WITH QSE*
-01	(4.27) .168	(5.00) .197
-02	(7.26) .286	(8.00) .315
-03	(10.27) .404	(11.00) .433
-04	(15.25) .600	(16.00) .630
-05	(18.26) .718	(19.00) .748
-07	(24.24) .954	(25.00) .984
-09	(13.26) .522	(14.00) .551

*Processing conditions will affect mated height. See SO Series for board space tolerances